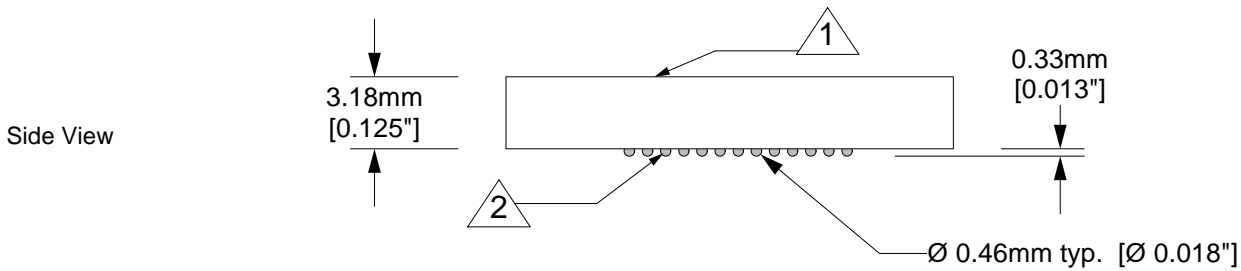
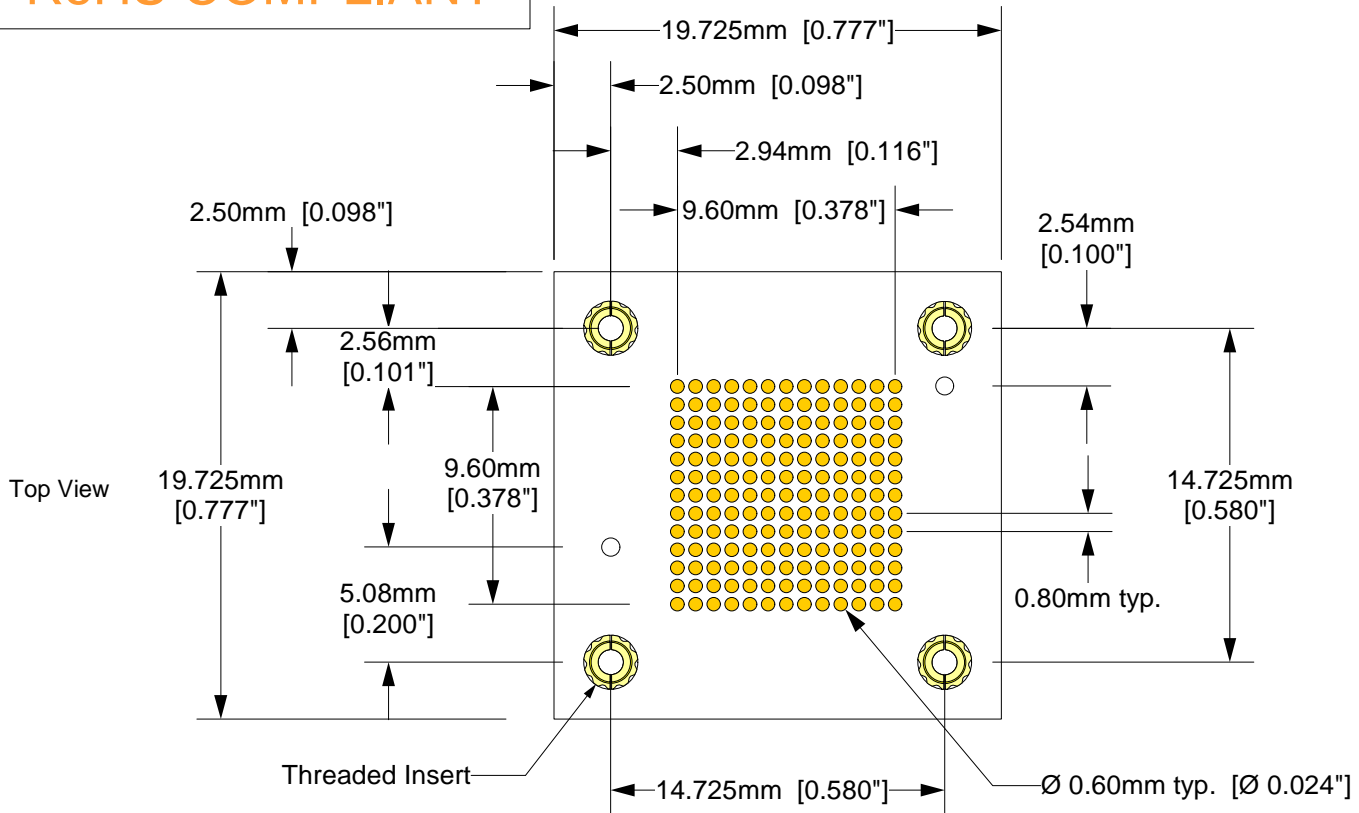


RoHS COMPLIANT



Substrate: 3.18mm \pm 0.25mm [0.125" \pm 0.001"] FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. Au plating. (RoHS)




Solder ball: Sn96.5Ag3.0Cu0.5

Description: BGA Surface Mount Adaptor

169 position surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p>© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400 Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>SF-BGA169F-B-05F Drawing</p>	<p>Status: Released</p>	<p>Scale: 3:1</p>	<p>Rev: A</p>
	<p>Drawing: S.Natarajan</p>	<p>Date: 5/13/06</p>		<p>Modified:</p>
	<p>File: SF-BGA169F-B-05F Dwg</p>			